Title: **Chip scale package with flip chip interconnect**

Inventor: Rajendra PENDSE *et al.*
Appln. No. 10/081,491

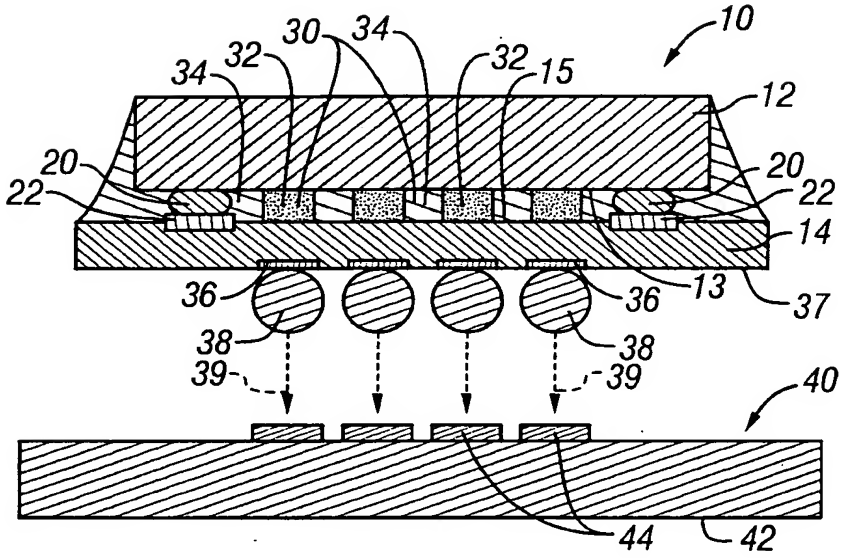

FIG. 1